

LPCVD doped polysilicon with in-situ tunnel oxide

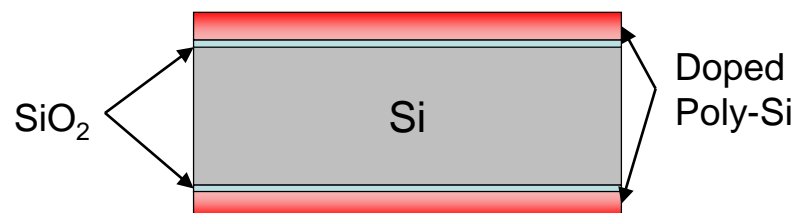
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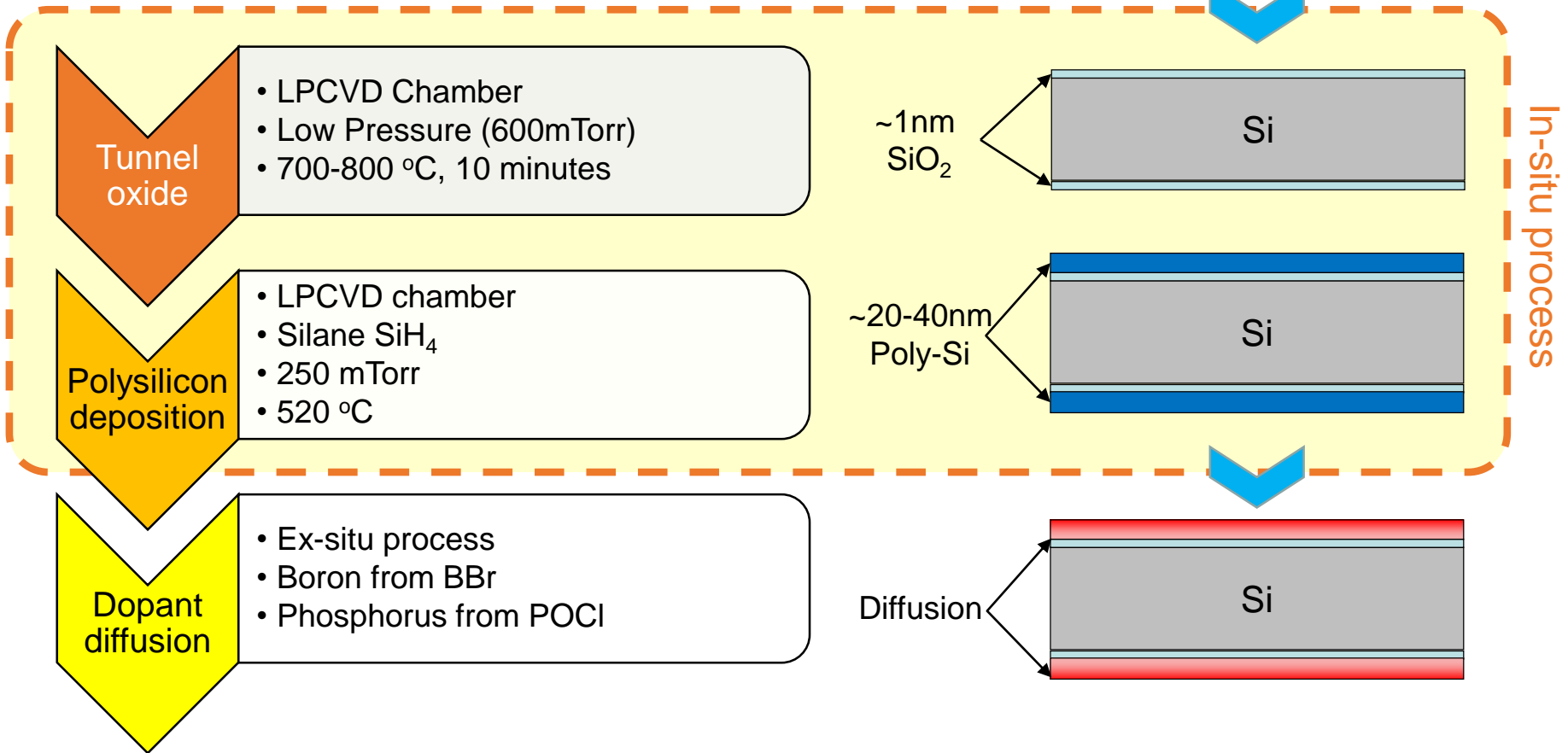
LPCVD polysilicon at ANU

- Furnace retrofit in 2015: collaborative project between ANU-Tempress-ARENA.
- Includes Silane, and Oxygen.
- Enabling low pressure in-situ oxidation for the Poly-Ox deposition.



Fabrication Process

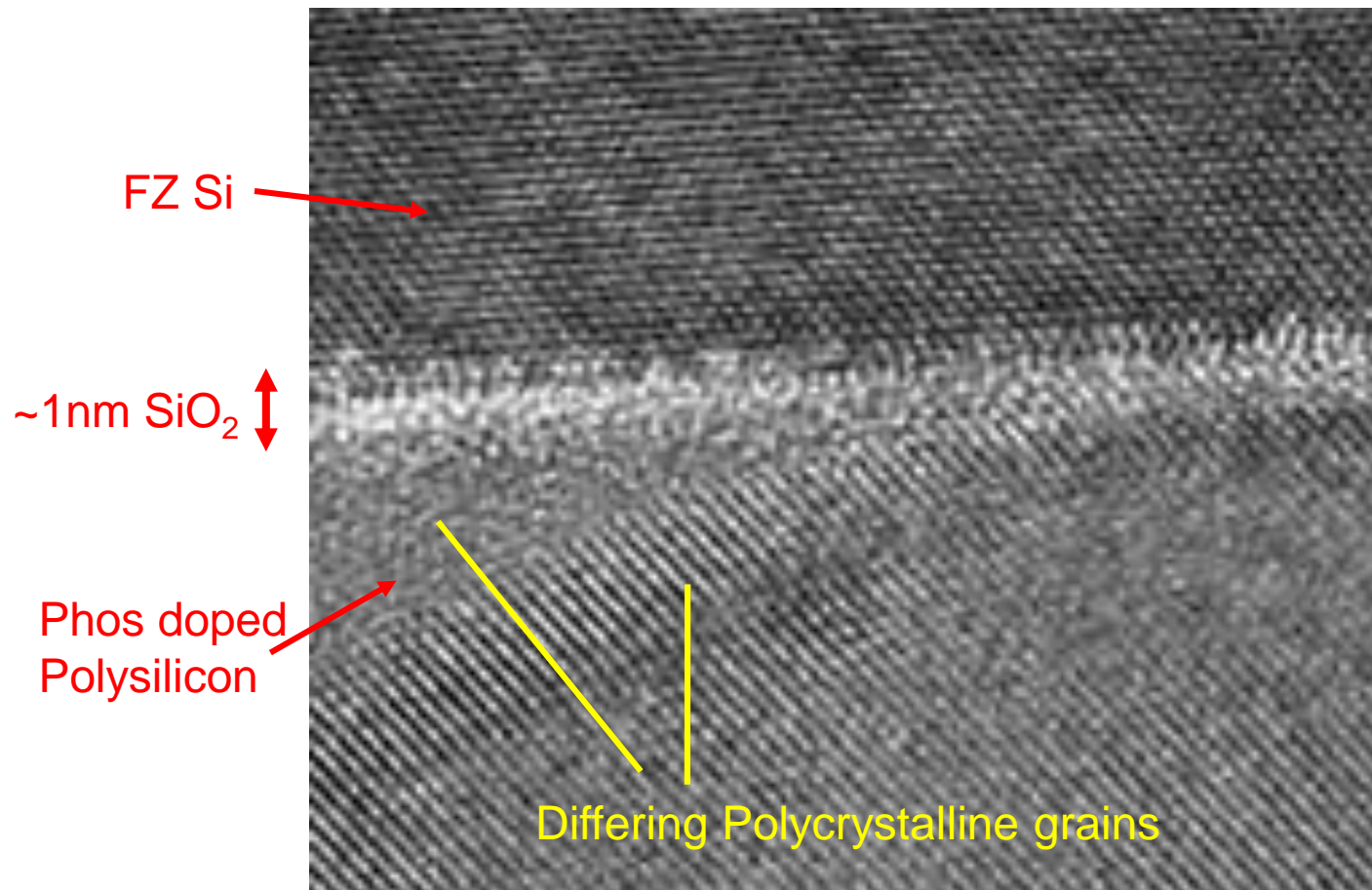
Diffused LPCVD Poly-Ox fabrication sequence



TEM of Poly-Ox layer

TEM of Phosphorus difused Poly-Ox structure (after 900°C anneal)

- Oxide ~ 1 nm
Appears fuzzy on both sides, with no clear boundary.
- Poly-Si appears crystalline with numerous grains of varying crystal orientation



Passivation Quality

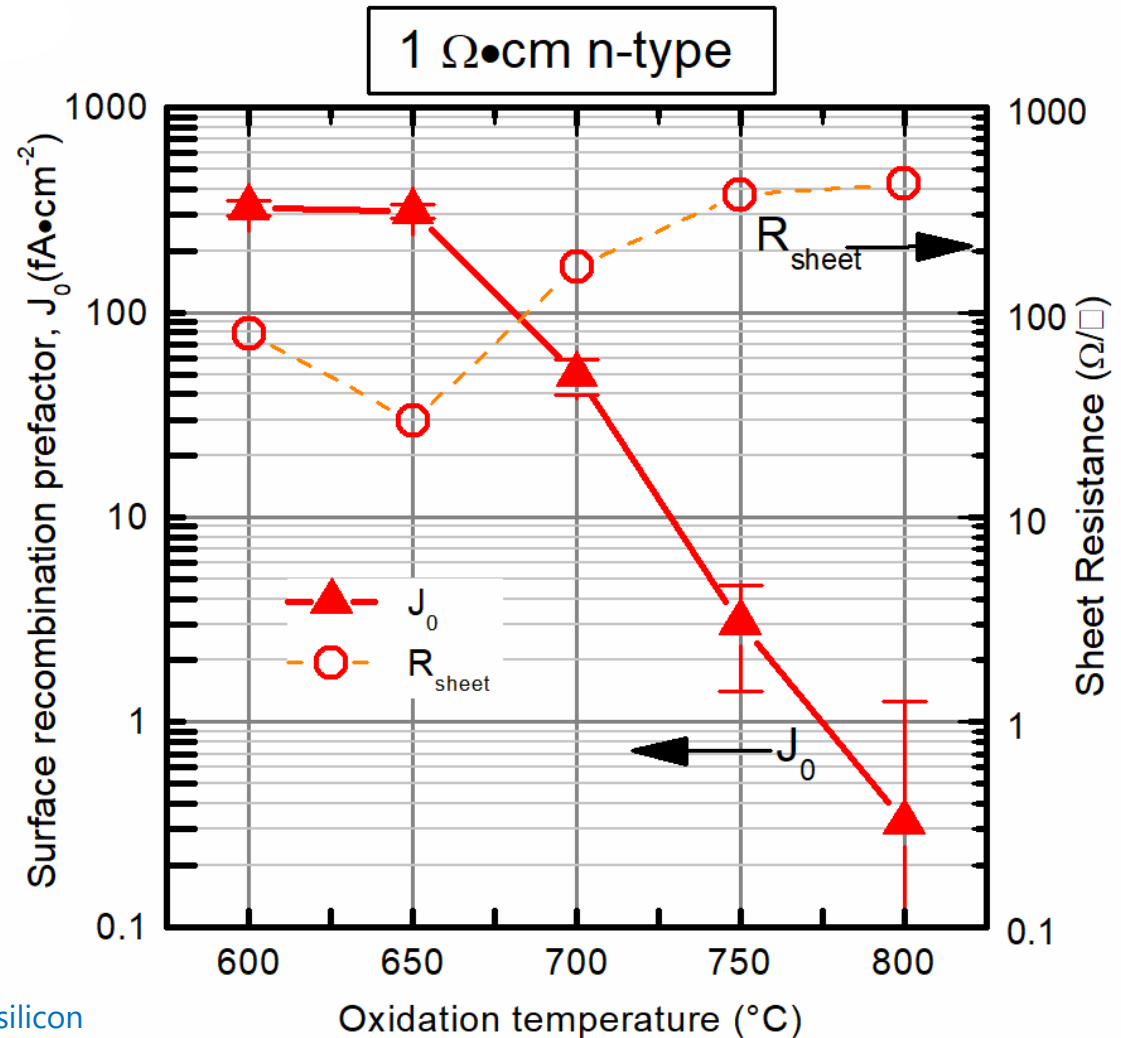
Best passivation of ~ 0.3 fA cm^{-2} is measured, with implied V_{OC} of 735mV.

Oxidation temperature is the key parameter.

Temp: 600-800 °C, 10mins,

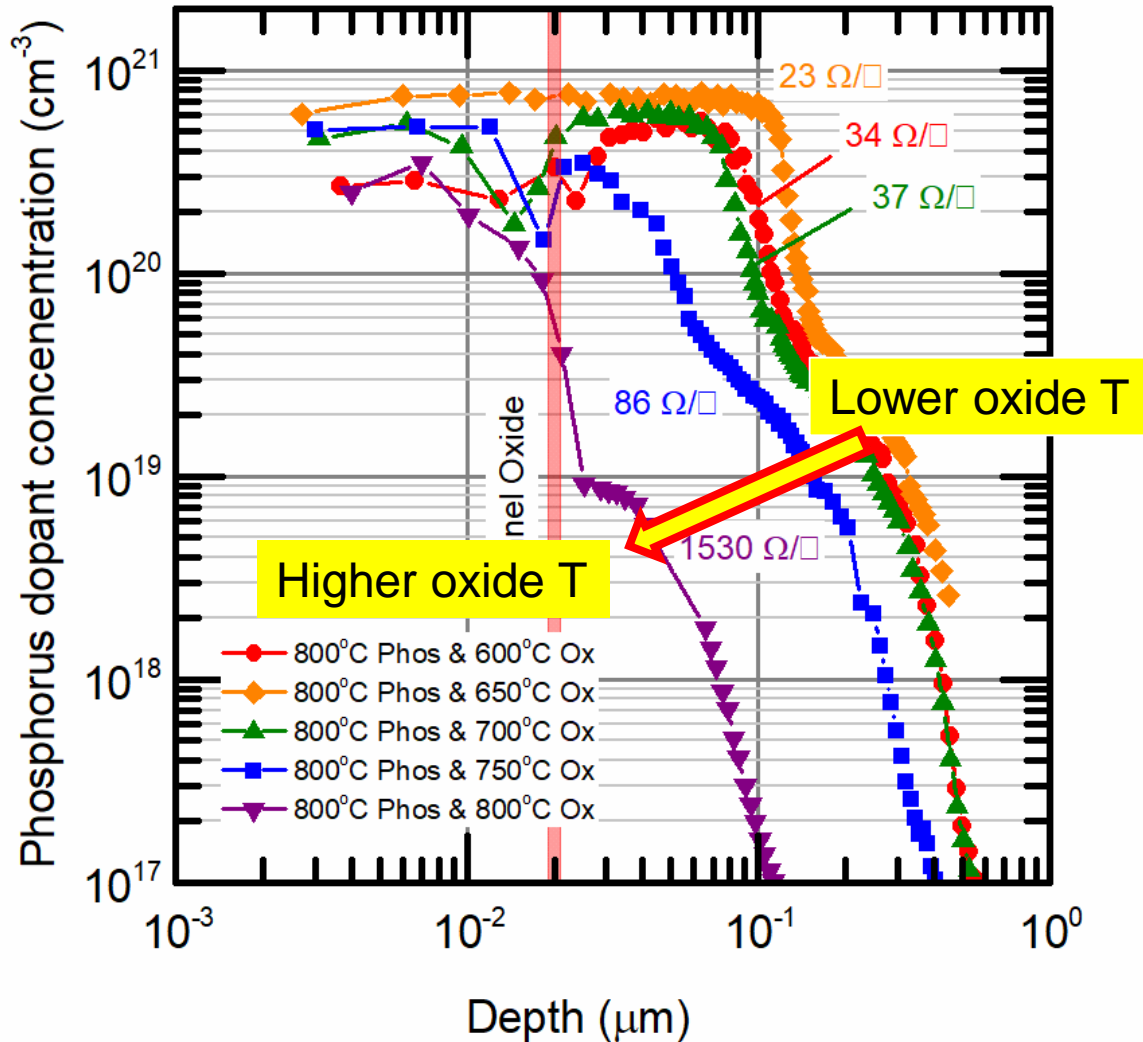
- $\text{SiO}_2 \rightarrow 1\text{-}1.2\text{nm}$
- $J_0 \rightarrow \sim 350\text{fA} - 0.3\text{fA}!$

Will be apparent from diffusion profile.



K. C. Fong *et al.*, "Phosphorus diffused LPCVD polysilicon passivated contacts with in-situ low pressure oxidation," *SOLMAT*, 2018.

Diffusion Profiles



Diffusion profile is extremely sensitive to oxide growth condition

Ox Temp: 600-800 °C

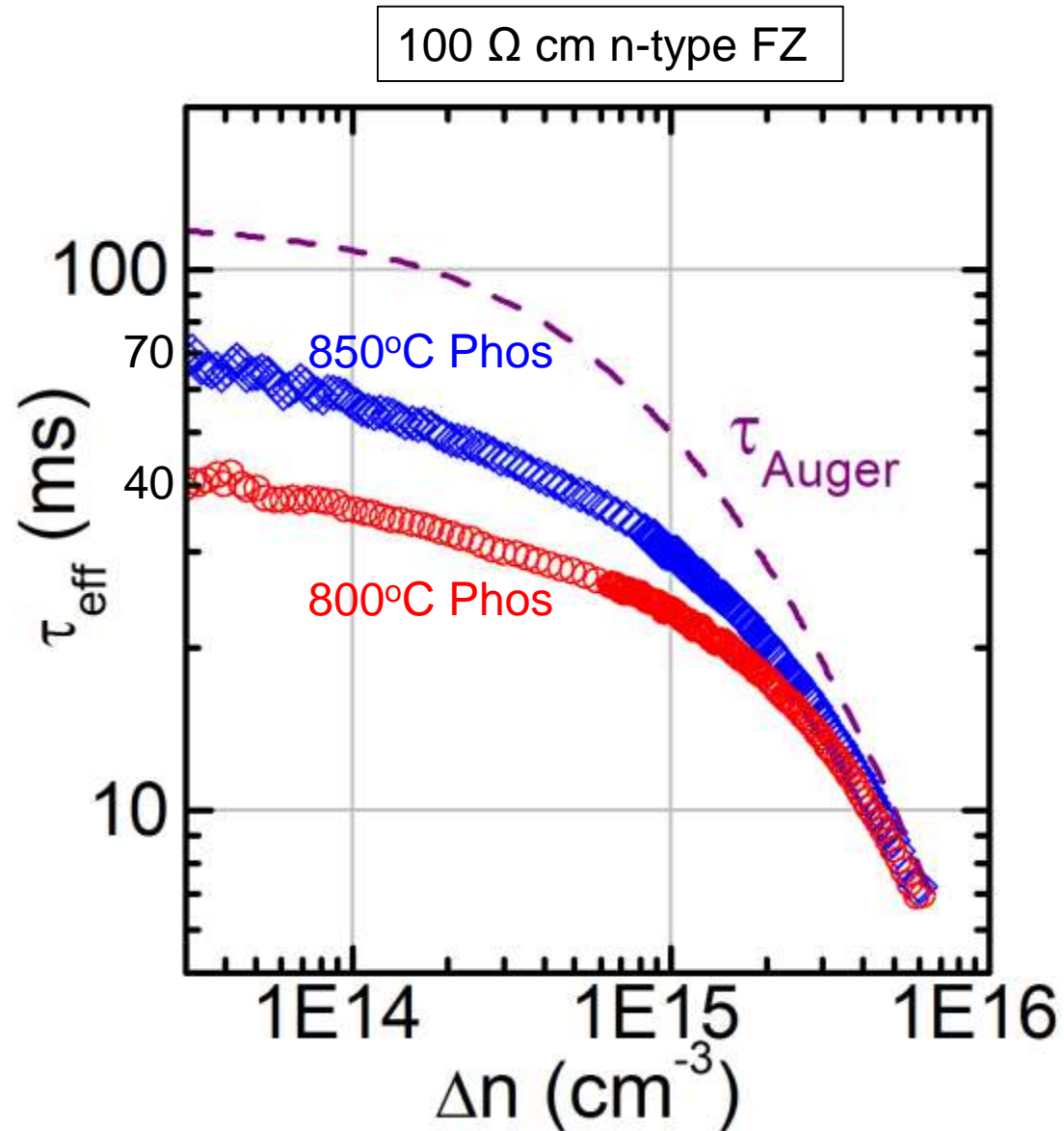
- $\text{SiO}_2 \rightarrow 1\text{-}1.2\text{nm}$
- $J_0 \rightarrow \sim 350\text{fA} - 0.3\text{fA}$
- $R_{\text{sheet}} \rightarrow 23 \Omega/\square$ to $1530 \Omega/\square$

To achieve $<1\text{fAcm}^2$, there must be only a small amount of dopant penetration to the wafer bulk, so as to avoid massive Auger recombinations.

This highlights the importance of excellent control in oxide growth conditions.

Using High-res n-type:

- High effective lifetimes above 70ms can be achieved.
- 735mV i-Voc

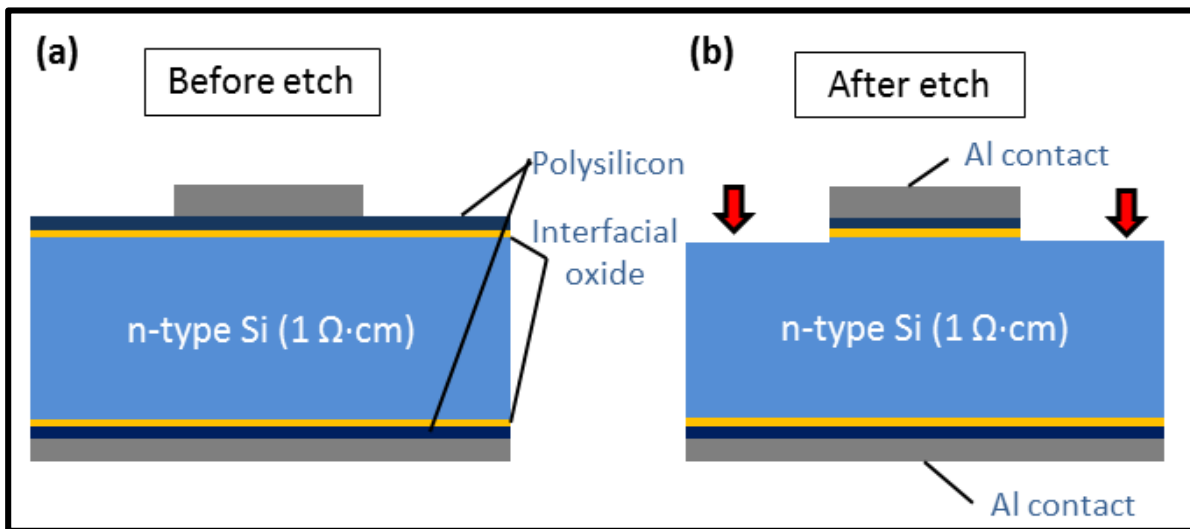


Contact Resistance

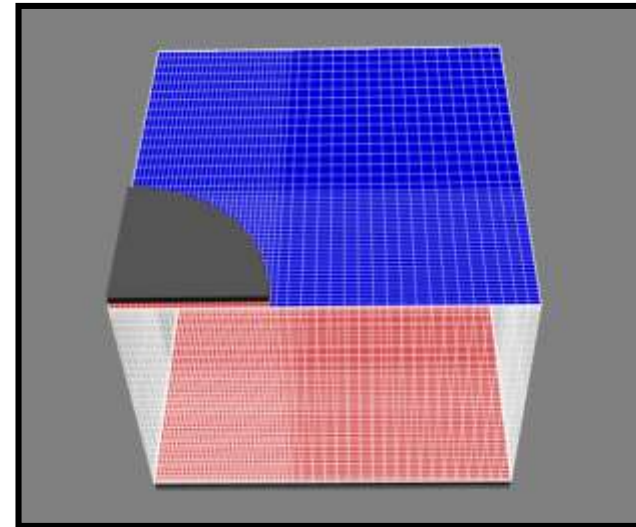
Modified Cox & Strack circular dot structure

- Using the lifetime sample, we evaporate metal dots, and etch surrounding poly-Ox
- This allows the use of the same wafer for lifetime & contact measurement.
- I-V curve is measured & ρ_c is calculated via iterative fitting to 3D ohmic model, assuming symmetrical front & rear ρ_c

Test structure (cross section)



3D model

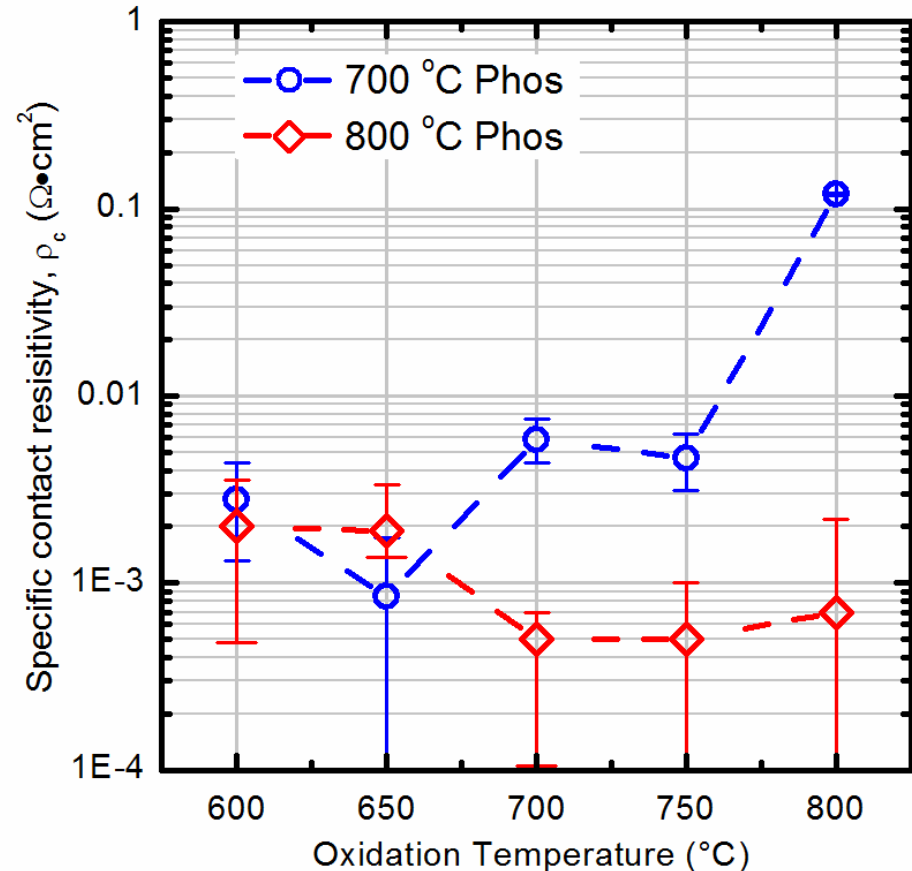


Contact Resistance

Excellent contact resistance below $1 \text{ m}\Omega \text{ cm}^2$ is measured for a wide range of conditions.

Large error bars:

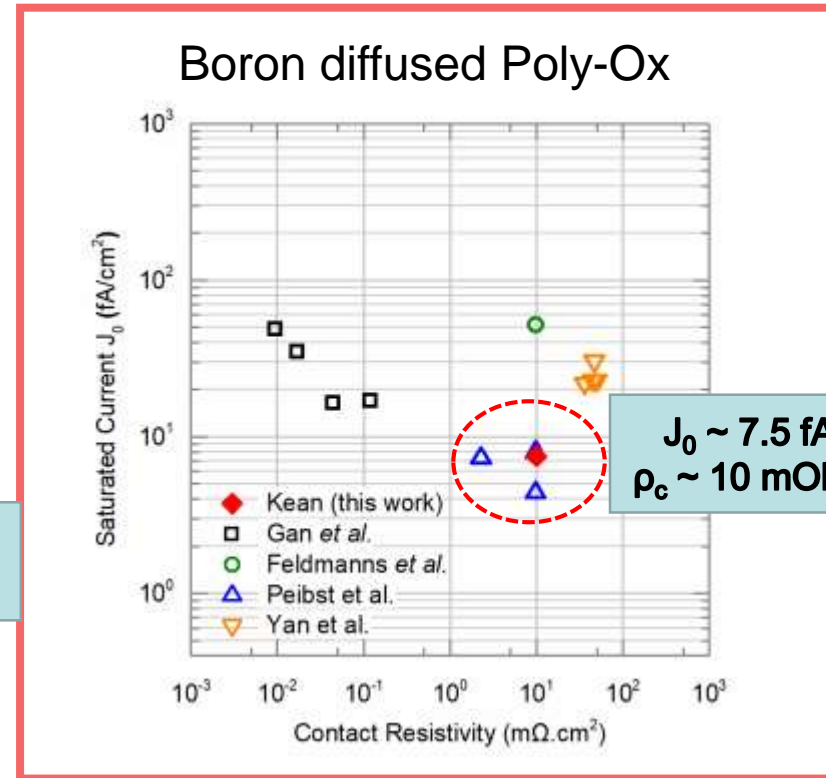
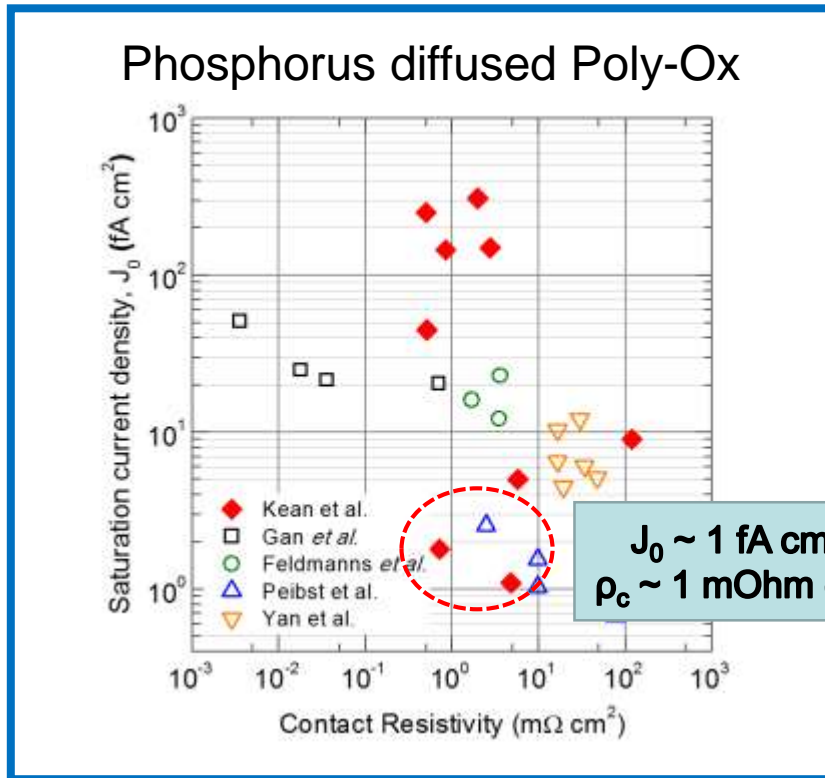
- Bulk resistance limits the accuracy of the method to $\sim 1 \text{ m}\Omega \text{ cm}^2$.



K. C. Fong *et al.*, IEEE Conference Proceedings, 2018.

Passivation vs Contact R

Comparing to literature, we are on par if not better than the best reported values:



K. C. Fong et al., "Phosphorus diffused LPCVD polysilicon passivated contacts with in-situ low pressure oxidation," *SOLMAT*, 2018.

This work:

- Demonstrated $J_0 < 1 \text{ fA cm}^{-2}$, $\rho_c < 1 \text{ m}\Omega \text{ cm}^2$ with phosphorus diffused LPCVD Poly-Ox
- Key novelty of in-situ process for Poly-Ox & low pressure oxidation step. Providing excellent process control.
- High bulk lifetimes $\sim 70\text{ms}$, with $iV_{oc} \sim 735\text{mV}$.

Future:

- Boron doped LPCVD Poly-Ox
- Application to cells, PERL, IBC, Bifacials
- Open to collaborations (Cell fabrication, tandem devices, etc)

Acknowledgements

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Specific ACAP contributions to this work:

- ACAP PP1: Silicon Solar Cells
- ACAP PP6.32: Optical Properties of Passivated Contacts
- ACAP Fellowship: Transparent Doped LPCVD Polysilicon Passivated Contacts

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